



PRODUCT SPECIFICATION

DOCUMENT NO.ENS000066640				
DESCRIPTION	DRAWN BY	DESIGNED BY	CHECKED BY	APPROVED BY
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**HCM1012G SERIES LOW PROFILE TYPE (Chip Common Mode Filter)
Engineering Specification**



This product belongs to the 3C and industrial grade standard, not for automotive application. If customer privately uses to automotive parts and results in any consequences, INPAQ is not responsible for after-sales service, thank you!

Features and Application

- Powerful components with composite co-fired material to solve EMI problem for high speed differential signal transmission line as USB, and LVDS, without distortion to high speed signal transmission.
- MIPI, MHL or HDMI, etc., serial interface in mobile device.

1.PRODUCT DETAIL

Part No.	Imp. Com. (Ω)±25% @100MHz	DCR Max. (Ω)	Rated Current Max.(mA)	Rated Voltage (V)	Insulation Resistance Min.(MΩ)
HCM1012GD500A05PDG	50	1.5	100	10	100
HCM1012GD670A05PDG	67	1.5	100	10	100
HCM1012GD900B05PDG	90	3.0	100	10	100
HCM1012GS150A05PDG	15	0.8	100	10	100
Test Instruments	●Agilent E4991A RF IMPEDANCE / MATERIAL ANALYZER ●HP4338 MILLIOHMMETER ●Agilent E5071C ENA SERIES NETWORK ANALYZER ●Keithley 2410 1100V SOURCE METER				

2.PART NUMBER CODE

<u>HCM</u>	<u>1012</u>	<u>G</u>	<u>□</u>	<u>90</u>	<u>0</u>	<u>□</u>	<u>05</u>	<u>P</u>	<u>DG</u>
1	2	3	4	5	6	7	8	9	10

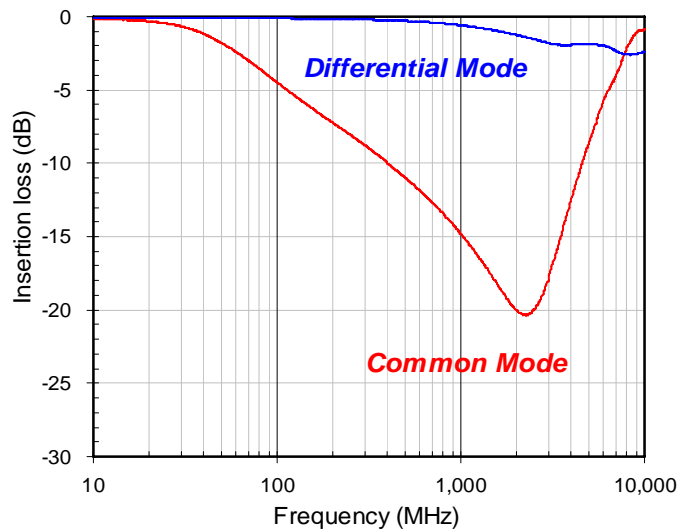
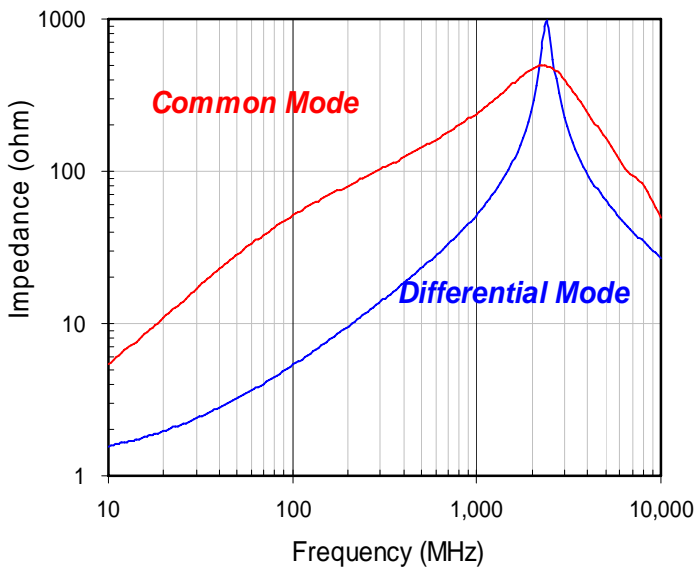
- 1 : Series name
- 2 : Dimensions L*W
- 3 : Material code
- 4 : Product identification number
- 5 : Impedance value (ex : 900=90Ω)
- 6 : Fixed decimal point
- 7 : INPAQ internal code
- 8 : Dimension T (ex : 05=0.50mm)
- 9 : Packaging style P – Paper tape, 7”reel.
- 10 : INPAQ internal code

3.TYPICAL CHARACTERISTIC

HCM1012GD500A05

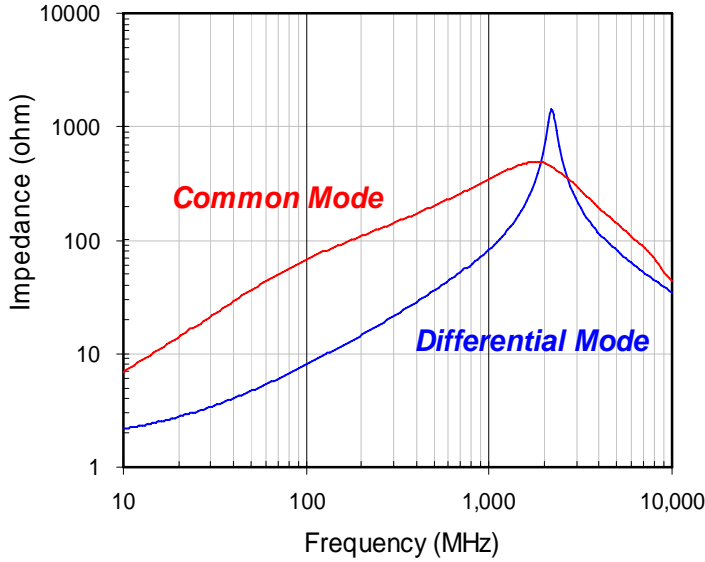
IMPEDANCE vs. FREQUENCY CHARACTERISTICS

INSERTION LOSS vs. FREQUENCY CHARACTERISTICS

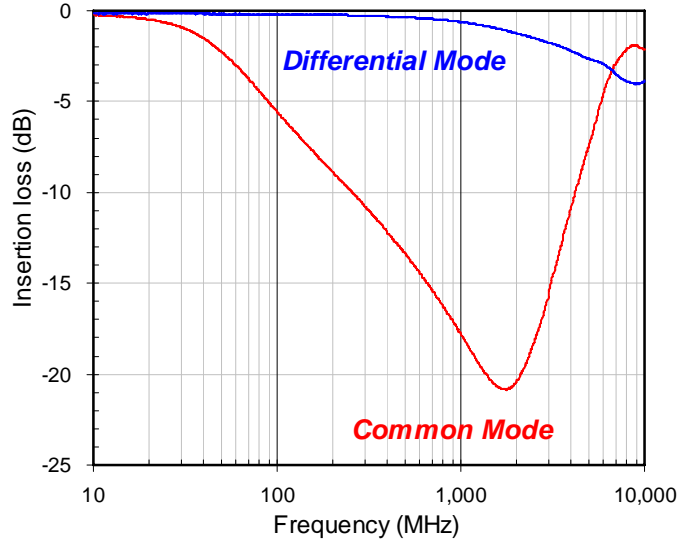


HCM1012GD670A05

IMPEDANCE vs. FREQUENCY CHARACTERISTICS

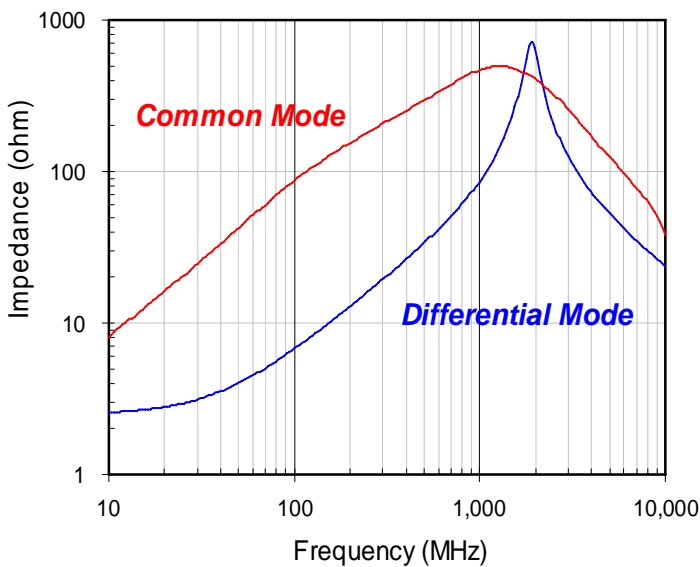


INSERTION LOSS vs. FREQUENCY CHARACTERISTICS

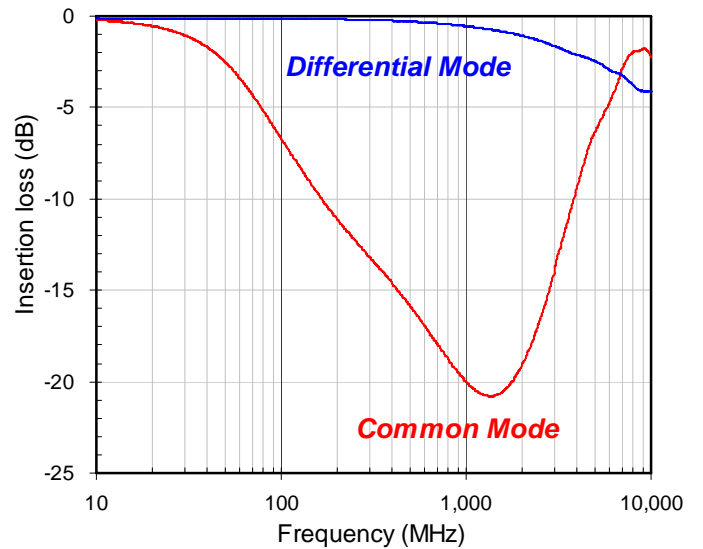


HCM1012GD900B05

IMPEDANCE vs. FREQUENCY CHARACTERISTICS

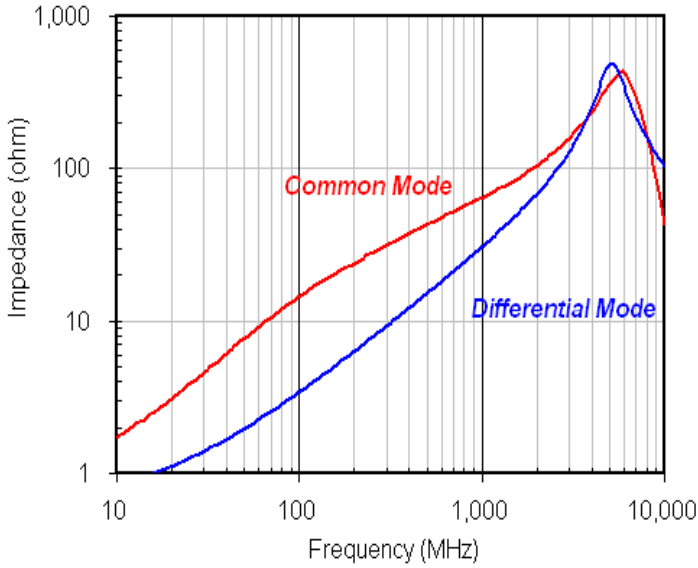


INSERTION LOSS vs. FREQUENCY CHARACTERISTICS

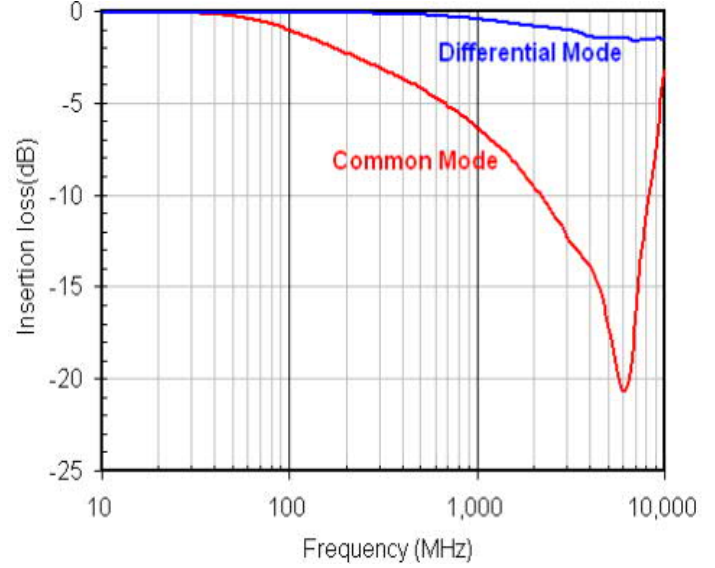


HCM1012GS150A05

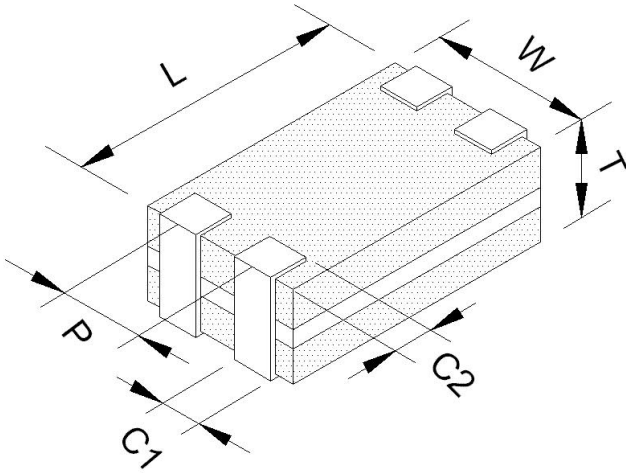
IMPEDANCE vs. FREQUENCY CHARACTERISTICS



INSERTION LOSS vs. FREQUENCY CHARACTERISTICS

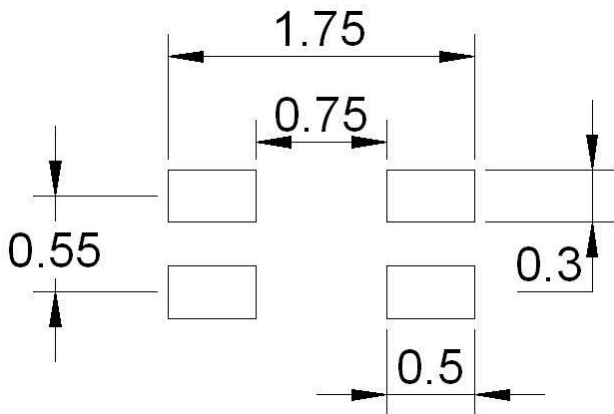
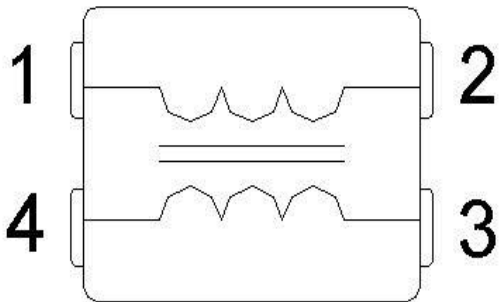


4. SHAPES AND DIMENSIONS



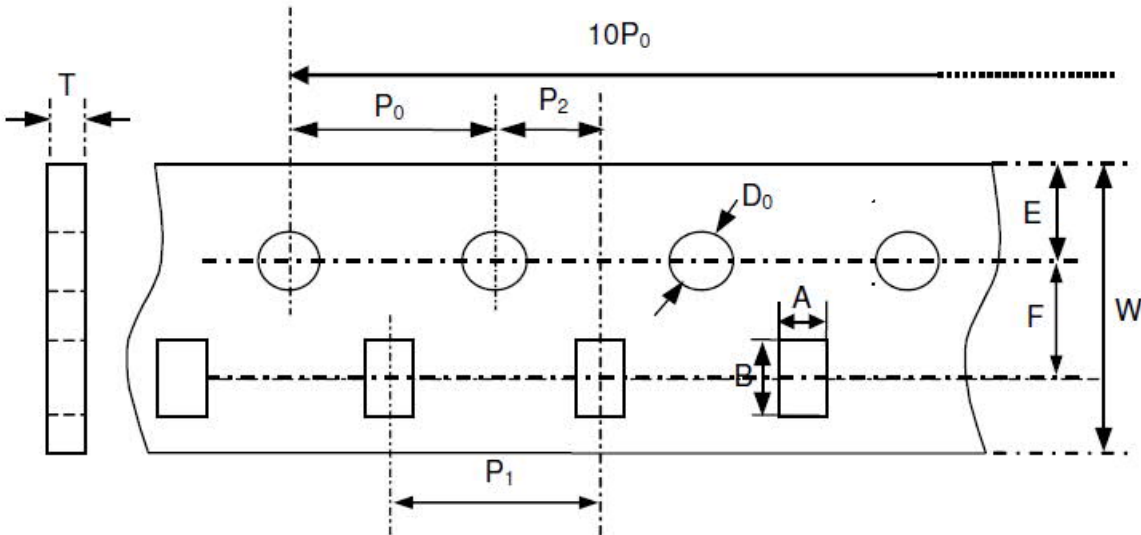
TYPE	Dimension
L	1.25±0.10
W	1.00±0.10
T	0.50±0.10
P	0.55±0.10
C1	0.30±0.10
C2	0.20±0.15
Unit : mm	

5. CIRCUIT CONFIGURATION & LAYOUT PAD



6.TAPE AND REEL SPECIFICATIONS/ TAPING DIMENSIONS

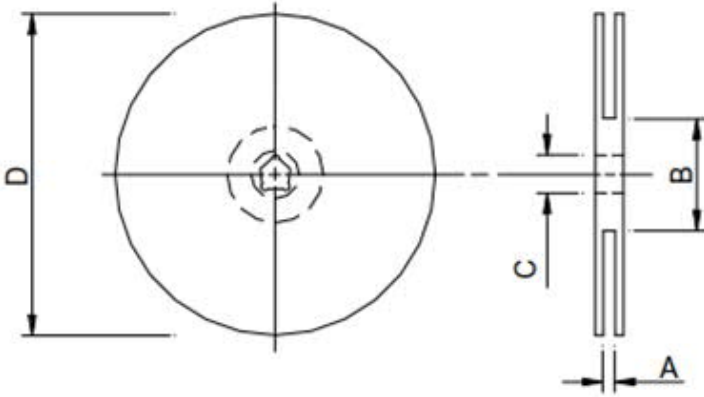
Type : Paper Carrier



Unit : mm

Symbol	Size	Symbol	Size
A	1.20±0.05	Po	4.00±0.10
B	1.45±0.05	P1	4.00±0.10
W	8.00±0.10	P2	2.00±0.05
E	1.75±0.05	Do	1.55±0.05
F	3.50±0.05	T	0.60±0.03

7. REEL DIMENSIONS

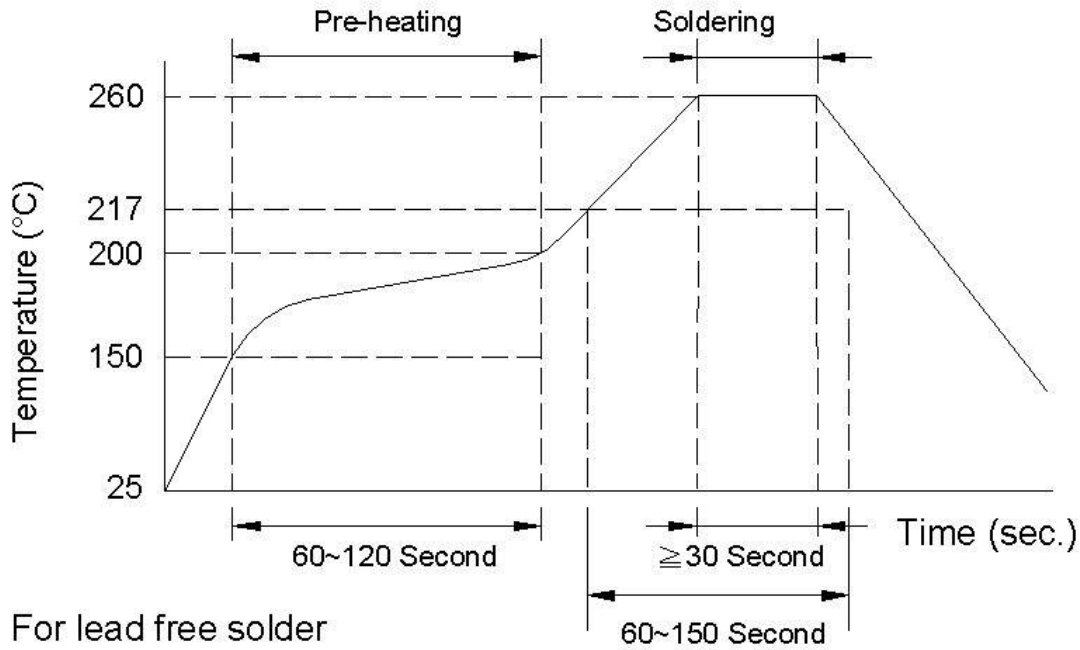


Type	A(mm)	B(mm)	C(mm)	D(mm)
7"	10±1.5	50 or more	13.2±1.0	178±2.0

8. STANDARD QUANTITY FOR PACKAGING

Packaging style : Taping
 Reel packaging quantity : 4000 pcs/reel
 Inner box : 5 reel/inner box

9.RECOMMENDED SOLDERING CONDITIONS



10.GENERAL TECHNICAL DATA

- Operating temperature range : - 40°C ~ +85°C
- Storage Condition : Less than 40°C and 70% RH
- Storage Time: 6 months Max.
- Soldering method: Reflow

11.RELIABILITY AND TEST CONDITION

Test item	Test condition	Criteria
Thermal Shock	A. Temperature : -40 ~ +85°C B. Cycle : 100 cycles C. Dwell time : 30minutes Measurement : at ambient temperature 24 hrs after test completion	A. No mechanical damage B. Impedance value should be within ± 20 % of the initial value
Operational Life	A. Temperature : 85°C \pm 5°C B. Test time : 1000 hrs C. Apply current : full rated current Measurement : at ambient temperature 24 hrs after test completion	A. No mechanical damage B. Impedance value should be within ± 20 % of the initial value
Biased Humidity	A. Temperature : 40 \pm 2°C B. Humidity : 90 ~ 95 % RH C. Test time : 1000 hrs D. Apply current : full rated current Measurement : at ambient temperature 24 hrs after test completion	A. No mechanical damage B. Impedance value should be within ± 20 % of the initial value
Resistance to Solder Heat	A. Solder temperature : 260 \pm 5°C B. Flux : Rosin C. DIP time : 10 \pm 1 sec	A. More than 95 % of terminal electrode should be covered with new solder B. No mechanical damage C. Impedance value should be within ± 20 % of the initial value
Steam Aging Test	A. Temperature : 93 \pm 2°C B. Test time : 4 hrs C. Solder temperature : 235 \pm 5°C D. Flux : Rosin E. DIP time : 5 \pm 1 sec	More than 95 % of terminal electrode should be covered with new solder